

Application No. 09/681,304

RD-28435

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: R.J. Saia et al.

Application No. 09/681,304

Filed: 15 March 2001

: Group Art Unit: 2814

: Examiner: D. Nguyen

: Response to Paper No. 8

TECHNOLOGY CENTER 2800

For **Microelectromechanical System
Device Package and Packaging Method**

AMENDMENT UNDER 37 CFR 1.111

Assistant Commissioner for Patents
Washington, DC 20231

In response to the Office Action dated 26 August 2002, please amend the above-identified
application as follows.

IN THE TITLE:

Replacement Title: Microelectromechanical System Device Packaging Method

IN THE CLAIMS:

Please rewrite claims 4 and 6 as follows:

Claim 4 (amended two times). The method of claim 1, wherein attaching the MEMS device
comprises using the adhesive.

Claim 6 (amended two times). The method of claim 1, wherein the adhesive comprises a mixture
of photodielectric and epoxy materials.

9/18/02
C. Stanley
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